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Amendments to the Specification:

Please replace the paragraph beginning at page 11, line 15 with the following amended paragraph:

For example, as shown in Fig. 1G, the silicon substrate 104 having the polymer pattern 108 formed thereon is subjected to a reactor 120 containing therein an electroless plating solution 112. As a result, as shown in Fig. 1H, a thin film micro-pattern 114', e.g., made of Al or Cu, having a desired thickness grows on certain portions of the surface of the silicon substrate 104 where no polymer pattern is remained remains.

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